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November 2016

FDMC007N08LC

N-Channel Shielded Gate PowerTrench® MOSFET 80 V, 66 A, 7.0 m Ω

Features

- Shielded Gate MOSFET Technology
- Max $r_{DS(on)}$ = 7.0 m Ω at V_{GS} = 10 V, I_D = 21 A
- Max $r_{DS(on)}$ = 10.4 m Ω at V_{GS} = 4.5 V, I_D = 17 A
- 5V Drive Capable
- 50% lower Qrr than other MOSFET suppliers
- Lowers switching noise/EMI
- MSL1 robust package design
- 100% UIL tested
- RoHS Compliant

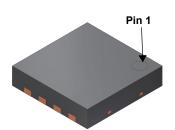


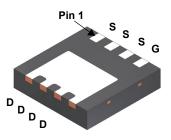
General Description

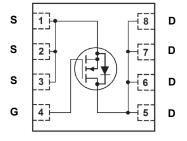
This N-Channel MV MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized to minimise on-state resistance and yet maintain superior switching performance with best in class soft body diode.

Applications

- Primary DC-DC MOSFET
- Synchronous Rectifier in DC-DC and AC-DC
- Motor Drive
- Solar







Top Power 33 Bottom

MOSFET Maximum Ratings TA = 25 °C unless otherwise noted

Symbol	Paramo	eter		Ratings	Units
V_{DS}	Drain to Source Voltage			80	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T _C = 25 °C	(Note 5)	66	
	-Continuous	T _C = 100 °C	(Note 5)	42	
I _D	-Continuous	T _A = 25 °C	(Note 1a)	14	Α
	-Pulsed		(Note 4)	330	
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	150	mJ
P _D	Power Dissipation	T _C = 25 °C		57	W
	Power Dissipation	T _A = 25 °C	(Note 1a)	2.4	VV
T _J , T _{STG}	Operating and Storage Junction Tempera	ature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case		2.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (No	te 1a)	53	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDMC007N08L	FDMC007N08LC	Power 33	13 "	12 mm	3000 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

Parameter

Off Char	racteristics					
BV_{DSS}	Drain to Source Breakdown Voltage	I _D = 250 μA, V _{GS} = 0 V	80			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, referenced to 25 °C		45		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 64 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V			100	nA

Test Conditions

Min

Max

Тур

Units

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 120 \mu A$	1.0	1.5	2.5	V
ΔV _{GS(th)}	Gate to Source Threshold Voltage Temperature Coefficient	I _D = 120 μA, referenced to 25 °C		-5.4		mV/°C
		V _{GS} = 10 V, I _D = 21 A		5.7	7.0	
r _{DS(on)}	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 17 \text{ A}$		8.3	10.4	mΩ
, ,		V_{GS} = 10 V, I_D = 21 A, T_J = 125 °C		9.9	12.2	
g _{FS}	Forward Transconductance	V _{DS} = 5 V, I _D = 21 A		80		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V = 40 V V = 0 V		2100	2940	pF
Coss	Output Capacitance	V _{DS} = 40 V, V _{GS} = 0 V, f = 1 MHz		506	710	pF
C _{rss}	Reverse Transfer Capacitance			18	30	pF
R_g	Gate Resistance		0.1	0.4	8.0	Ω

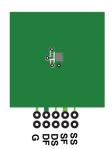
Switching Characteristics

t _{d(on)}	Turn-On Delay Time		10	20	ns
t _r	Rise Time	V _{DD} = 40 V, I _D = 21 A,	2.4	10	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{GEN} = 6 Ω	24	39	ns
t _f	Fall Time		2.1	10	ns
Q_g	Total Gate Charge	V _{GS} = 0 V to 10 V	29	41	nC
Q_g	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 40 \text{ V}$,	14	19	nC
Q _{gs}	Gate to Source Charge	I _D = 21 A	5		nC
Q _{gd}	Gate to Drain "Miller" Charge		3		nC
Q _{oss}	Output Charge	V _{DD} = 40 V, V _{GS} = 0 V	30		nC
Q _{svnc}	Total Gate Charge Sync.	V _{DS} = 0 V, I _D = 21 A	27		nC

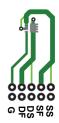
Drain-Source Diode Characteristics

V _{SD}	Source to Drain Diode Forward Voltage	$V_{GS} = 0 V, I_{S} = 2 A$	(Note 2)	0.1	0.7	1.2	W
	Source to Drain Diode Forward voltage	$V_{GS} = 0 \text{ V}, I_{S} = 21 \text{ A}$	(Note 2)	0.1	0.8	1.3	\ \ \
t _{rr}	Reverse Recovery Time	-I _F = 10 A, di/dt = 300 A/μs			20	32	ns
Q _{rr}	Reverse Recovery Charge				27	43	nC
t _{rr}	Reverse Recovery Time	I _F = 10 A, di/dt = 1000 A/μs			14	22	ns
Q _{rr}	Reverse Recovery Charge				62	99	nC

^{1.} R_{0,1A} is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. R_{0,0A} is determined by the user's board design.



a. 53 °C/W when mounted on a 1 in² pad of 2 oz copper



b. 125 °C/W when mounted on a minimum pad of 2 oz copper

^{2.} Pulse Test: Pulse Width < 300 µs, Duty cycle < 2.0%.
3. E_{AS} of 150 mJ is based on starting T_J = 25 °C, L = 3 mH, I_{AS} = 10 A, V_{DD} = 80 V, V_{GS} = 10 V, 100% test at L = 0.1 mH, I_{AS} = 33 A.
4. Pulsed Id please refer to Fig 11 SOA graph for more details.
5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

Typical Characteristics T_J = 25 °C unless otherwise noted.

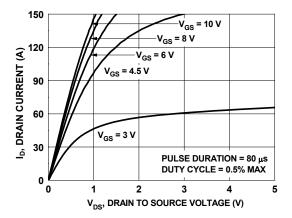


Figure 1. On Region Characteristics

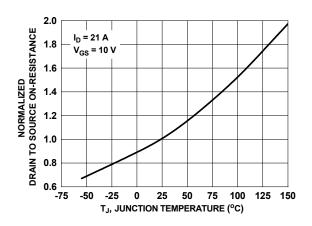


Figure 3. Normalized On Resistance vs. Junction Temperature

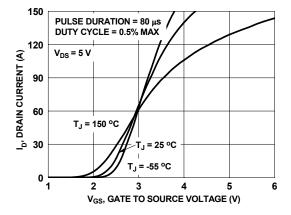


Figure 5. Transfer Characteristics

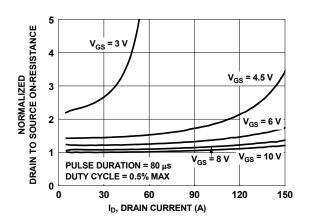


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

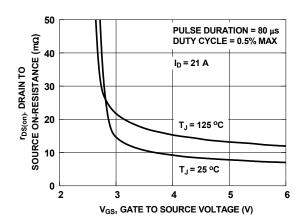


Figure 4. On-Resistance vs. Gate to Source Voltage

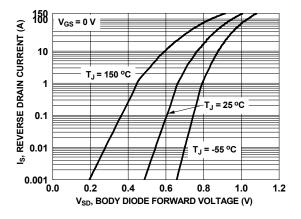


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics T_J = 25 °C unless otherwise noted.

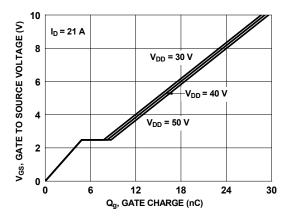


Figure 7. Gate Charge Characteristics

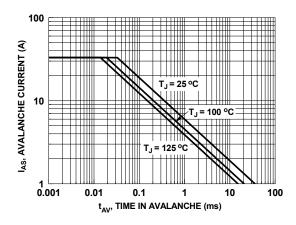


Figure 9. Unclamped Inductive Switching Capability

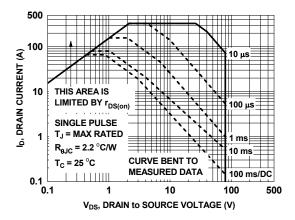


Figure 11. Forward Bias Safe Operating Area

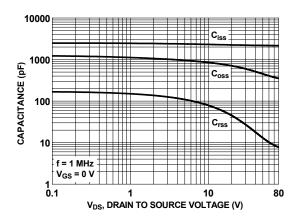


Figure 8. Capacitance vs. Drain to Source Voltage

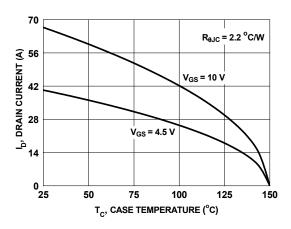


Figure 10. Maximum Continuous Drain Current vs Case Temperature

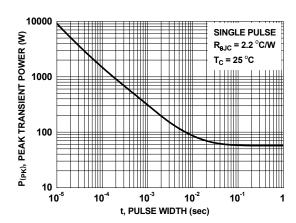


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

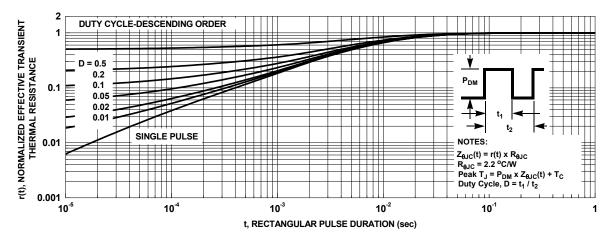
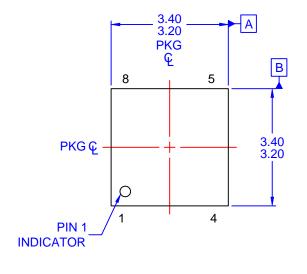
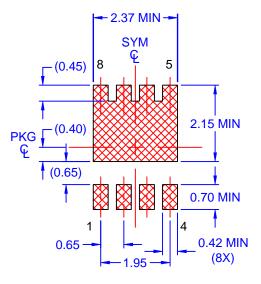
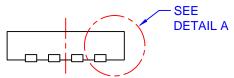


Figure 13. Junction-to-Case Transient Thermal Response Curve

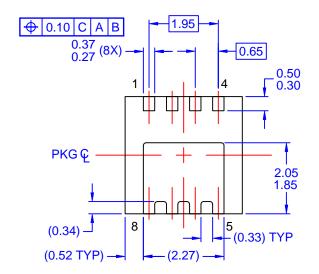
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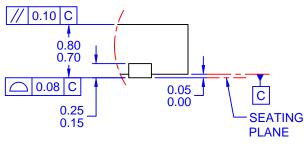


LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE STANDARD REFERENCE: JEDEC MO-240, ISSUE A, VAR. BA, DATED OCTOBER 2002.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
- D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- E) DRAWING FILE NAME: PQFN08HREV1



DETAIL A
SCALE: 2X

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